



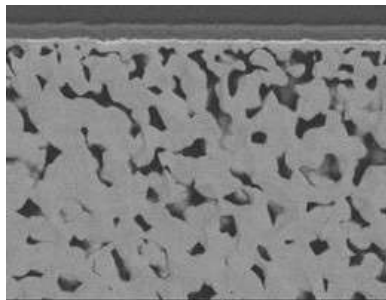
FOR IMMEDIATE RELEASE

CONTACT: Kevin McLaughlin, Product Manager
(408) 516-4611
info@namics-usa.com

NAMICS CORPORATION DEVELOPS IMPROVED SINTERED SILVER ADHESIVE

San Jose, CA—NAMICS Corporation has developed a sintered silver die attach paste (UNIMEC H9890-6A) for the semiconductor market. UNIMEC H9890-6A low-temperature sintered die attach paste using our Metallo-Organic (MO) technology. This high thermal conductive paste does not require pressure while curing, and the porous sintered structure has been reinforced by a proprietary resin system. This material has been developed for replacing eutectic solders offering the same thermal performance as AuSn solder.

UNIMEC H9890-6A is in full production and is available for sampling. Standard packaging is frozen syringes with 10 grams in a 5cc syringe; larger syringes are available. To find out more about these NAMICS sintered silver materials, please visit <http://www.namics.co.jp/e/product/unimec05.html> or contact your local NAMICS sales representative.



H9890-6A cross-section

NAMICS CORPORATION is a leading source for underfills, encapsulants, adhesives, and insulating and conductive materials used by producers of semiconductor devices, passive components and solar cells. Headquartered in Niigata, Japan with subsidiaries in the USA, Europe, Singapore, Korea, Taiwan and China, NAMICS serves its worldwide customers with enabling products for leading edge applications.

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